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Leybold Mag 2000C, 2000CT

Technical Specifications

Technical Data		TURBOVAC MAG 2000 C	TURBOVAC MAG 2000 CT
Inlet flange	**DN**	250 ISO-F	250 ISO-F
Pumping speed according to PNEUROP			
N_2	**l x s^{-1}**	1550	1550
He	**l x s^{-1}**	1780	1780
H_2	**l x s^{-1}**	1390	1390
Speed	**min^{-1}**	28 800	28 800
Compression ratio			
N_2		> 10^8	> 10^8
Ultimate pressure according to DIN 28 400	**mbar (Torr)**	< 10^{-8} (< 0.75 x 10^{-8})	< 10^{-8} (< 0.75 x 10^{-8})
Max. foreline pressure for N_2	**mbar (Torr)**	1.6 (1.2)	1.6 (1.2)
Recommended forevacuum pump			
Rotary vane pump		TRIVAC D 65 BCS	TRIVAC D 65 BCS
or dry compressing pump offering			
a pumping speed of 100 m^3/h			
Run-up time	**min**	< 8	< 8
forevacuum flange	**DN**	40 KF	40 KF
Purge / vent port	**VCR nut**	1/4"	1/4"
Cooling water connection			
(OD tube)	**mm (in.)**	6.4 (0.25)	6.4 (0.25)
Weight, approx.	**kg (lbs)**	68 (150)	68 (150)

Electronic frequency converter: MAG.DRIVE 2000

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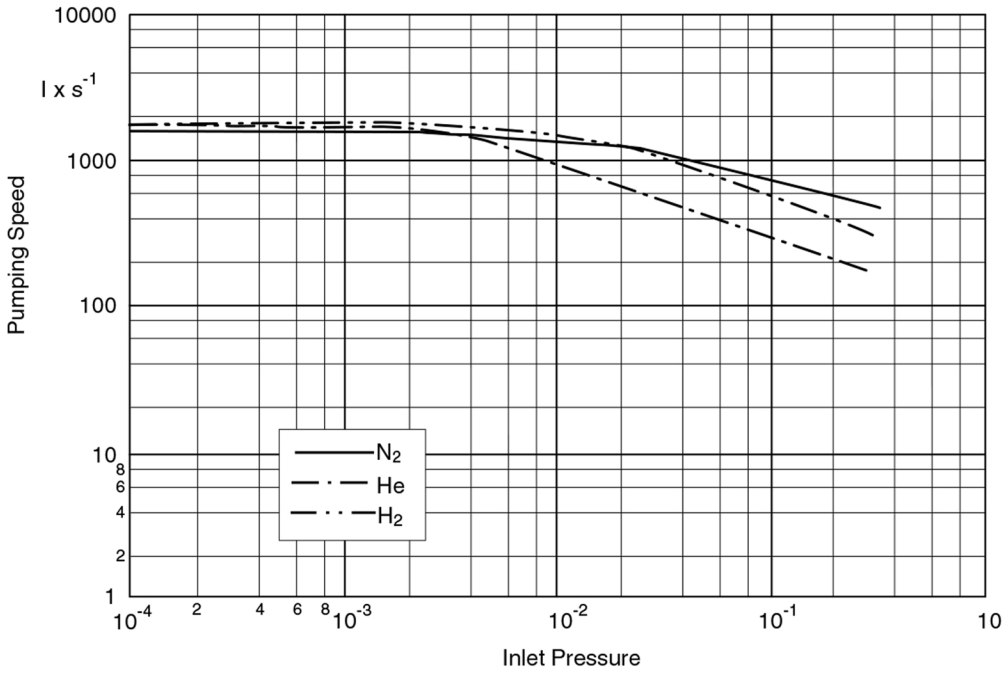
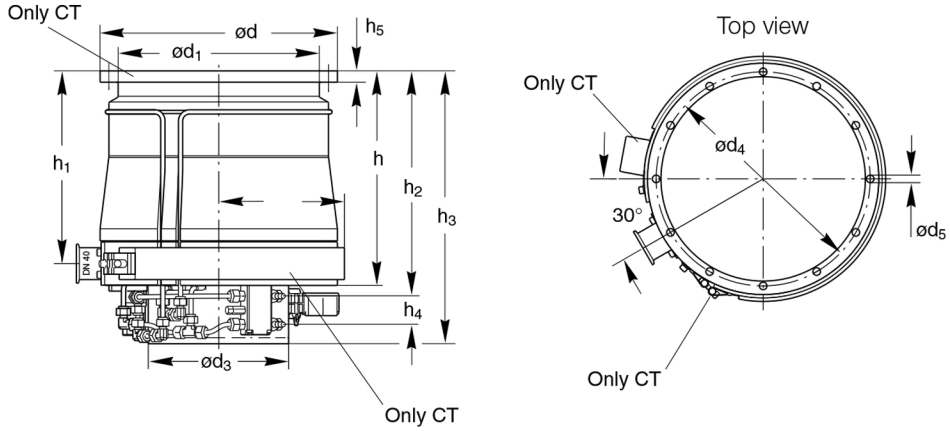
Pumping Curves



Pumping speed of the TURBOVAC MAG 2000 CT (DN 250) as a function of the inlet pressure

Dimensions



	d	d_1	d_2	d_3	d_4	d_5	h	h_1	h_2	h_3	h_4	h_5
mm	335	310	335	199	284	11	303	272	318	386	40	16
in.	13.19	12.20	13.19	7.83	11.18	0.43	11.93	10.71	12.52	15.20	1.57	0.63

Dimensional drawing for the TURBOVAC MAG 2000 C/CT

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Features & Benefits

- active 5-axis magnetic bearing system
- patented KEPLA-COAT® for rotor & stator to prevent corrosion
- low noise & vibration levels
- operation in any orientation
- advanced rotor design for high throughput
- integrated purge gas system
- CT versions: integrated temperature management system
- maintenance-free
- high throughput for all etch gases
- high pumping speed at low pressure
- high foreline pressure tolerance (up to 1.5 Torr)
- high resistance against corrosive gases
- robust against particles & deposits
- temperature management system to avoid condensation
- application specific design

Applications

- load locks • transfer chambers • all major semiconductor processes (etch, CVD, PVD, ion implantation